EMIL OTTO

Etimol SW 20 CN

Catalog-No. 5107

SMT-Stencil cleaning within automatic equipment

Field of Application

SMT-Stencil cleaning within automatic cleaning equipment

Customer benefits

Concentrate to dilute with DI-water. Efficient removal of solder paste and SMT-adhesive from stencils grants repeatable and stable cleaning process which helps to achive high-quality printing results. The waterbased formulation combines high flashpoint and work safety level and helps to eliminate flammable solvents from within the production area

Please consider approvals of equiment manufacturer!

Technical Data

Appearance / Consistancy:	Colorless to slightly yellow, clear	**Operations temperature:**	Room temperature
Application::	1 part concentrate : 4 parts DI water	**Reliable cleaning results with:**	Leaded, lead-free,no-clean solder pastes SMT-adhesives
Density at 20°C:	0,922 +/- 0,005 g/cm³	**Shelf life (month)**	36
pH-value	Neutral	**Storage conditions**	Ideal in original packaging at 10-25℃
Boiling point / bioling range:	>100℃	**Transportation:**	Non-DG
System:	Waterbased (ready-mix)	**Packaging:**	5 L blue plastic can 20 L green plastic can
Flashpoint:	None (ready-mix)		

Application notes:

The waterbased, pH-neutral cleaning concentrate is blended 1 part to 4 parts DI-water (equals ready diluted **Etimol SW 25 RAN**) to efficiantly remove leaded, lead-free, no-clean solder pastes and SMT-adhesives from SMT-stencils within automatic cleaing equipment. The innovative blend shows excellent dissolving properties that grant stable and high quality cleaning results and shows excellent rinsability with itself and DI-water.

The cleaning media is used straight at room temperature and put within the cleaning tank of the automatic equipment.

Consider approvals of equipment manufacturer!

Consider compatibility of SMT-stencil adhesive!